PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHIN-PUU JENG	11/01/2017
SHUO-MAO CHEN	11/01/2017
FENG-CHENG HSU	11/07/2017

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17875312

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ATTORNEY DOCKET NUMBER:	T1516.10356US04
NAME OF SUBMITTER:	R. BURNS ISRAELSEN
SIGNATURE:	/R. Burns Israelsen, Reg. No. 42685/
DATE SIGNED:	08/01/2022

Total Attachments: 2

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PATENT REEL: 060683 FRAME: 0253

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title)
PACKAGE STRUCTURE AND METHOD OF FORMING PACKAGE STRUCTURE
The PATENT RIGHTS referred to in this agreement are:
(check one) a patent application for this invention, executed by the ASSIGNOR(S)
concurrently with this assignment.
⊠U.S. patent application Serial No. <u>15/800,035</u> , filed <u>October 31, 2017</u>
☐a U.S. patent application based on PCT International Application
Nofiled on (date)(U.S. patent application
Serial No, if known).
U.S. patent No, issued
The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of
the patents and patent applications identified above.
The PATENT RIGHTS assigned under this agreement are:
(check one) ⊠U.S. patent rights only.
Worldwide patent rights. In this case, the assignee shall have the right to
claim the benefit of the filing date of any U.S. or foreign patent application
for this invention.
The $ASSIGNOR(S)$ referred to in this agreement is (or are) the inventor(s) whose signatures
appear on page 2 of this Assignment and any Supplemental Sheet(s).
The ASSIGNEE referred to in this agreement is:
(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,
TAIWAN 300, R.O.C.
The ASSIGNEE is:
(check one) ☐ An individual.
☐A Partnership.
A Corporation of <u>TAIWAN, R.O.C.</u> (specify state or country)
other)
The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and
valuable consideration, receipt of which is acknowledged, hereby assign(s) the following
rights to the ASSIGNEE, its successors and assigns:

rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

> **PATENT** REEL: 060683 FRAME: 0254

NP-20153-US/P20160960US00

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO
ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
INVENTION TITLE: PACKAGE STRUCTURE AND METHOD OF FORMING
PACKAGE STRUCTURE

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Shin-Puu JENG
Name of sole or first inventor

Signature

Shuo-Mao CHEN
Name of second inventor, if any

Signature

Signature

Signature

Date

Feng-Cheng HSU
Name of third inventor, if any

Signature

Signature

Date

PATENT REEL: 060683 FRAME: 0255

RECORDED: 08/01/2022